

Low-Cor 51

HEADER DIP & CORE BAKING FLUX

TYPICAL PROPERTIES

Appearance: Mobile clear amber liquid
pH: < 1.0

Description

Low-Cor 51 provides greater solder penetration due to excellent wetting. No Zinc Salt formation thus causes reduced water treatment. Cleaner solder surface resulting in a better core easier to paint. Low-Cor 51 has excellent heat stability. The super high concentration of Low-Cor 51 saves on shipping cost.

Recommended Application

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LOW-COR 51 super concentrate may be applied by a cascade or immersion.

Dilution Recommendations: Application Water :

Flux Core Bake 5:1 - 8:1 Header Dip 2:1 - 4:1 Torch

Soldering 1:0 - 2:1

Benefits

- * Used with wide range of solder.
- * Superior cleaning ability for removal of lubricants, shop dirt and oxides.
- * Concentration controlled by a simple titration procedure.
- * Excellent shelf life.
- * Better paint adhesion.
- * Engineered for radiator manufacturers and rebuilders
- * Leaves virtually no residues
- * Easier wastewater treatment
- * Increases shelf life of radiator

Health & Safety

Please refer to SDS for complete health and safety information.